

Materials Declaration

Package	SSOP
Body Size	5.3 mm
LeadCount	20
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	8.91 E-03	58766
SiO2 Filler	85	7.58 E-02	499508
Phenol Resin	3	2.67 E-03	17630
Antimony_Sb2O3	1.5	1.34 E-03	8815
Brominated Resin	0.5	4.46 E-04	2938

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	4.80 E-02	316614
Fe	2.35	1.16 E-03	7631
P	0.03	1.48 E-05	97
Zn	0.12	5.91 E-05	390

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	8.44 E-04	5563

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.56 E-03	16855

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	4.04 E-04	2663

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	8.59 E-03	56623

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	2.24 E-04	1477
Ag Filler	75	6.72 E-04	4430

Package Totals

Weight (g)	PPM
1.52 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability for any inaccuracy of such information.

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Option	Sn/Pb

Molding Compound

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P	0.03	1.48 E-05	97
Zn	0.12	5.91 E-05	390

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	8.44 E-04	5563

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.17 E-03	14327
Pb	15	3.84 E-04	2528

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	4.04 E-04	2663

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	8.59 E-03	56623

Die Attach

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